

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	137684	(multilayer (multi adj layer) ((metal conductor) with (insulation insulated insulating))) with (carrier body substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 12:48
L2	521791	(reinforce reinforcing reinforcement reinforced metal) with (sheet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 12:53
L3	4627	1 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 12:49
L4	717	(semiconductor die chip dice ic (integrated adj circuit)) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 12:53
L5	56	(bump ball bga) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 12:53
L6	590482	(reinforce reinforcing reinforcement reinforced metal) with (foil sheet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 12:53
L7	6889	1 same 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 12:53
L8	1130	(semiconductor die chip dice ic (integrated adj circuit)) same 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 12:53

L9	92	(bump ball bga) same 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/25 12:53
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